SDLS146A - OCTOBER 1976 - REVISED FEBRUARY 2002

- 3-State Outputs Drive Bus Lines Directly
- PNP Inputs Reduce dc Loading on Bus Lines
- Hysteresis at Bus Inputs Improves Noise Margins
- Typical Propagation Delay Times Port to Port, 8 ns

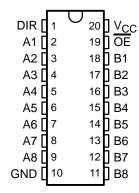
TYPE	I _{OL} (SINK CURRENT)	IOH (SOURCE CURRENT)
SN54LS245	12 mA	–12 mA
SN74LS245	24 mA	−15 mA

description

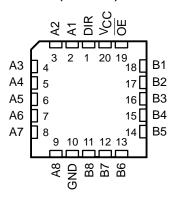
These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can disable the device so that the buses are effectively isolated.

SN54LS245 . . . J OR W PACKAGE SN74LS245 . . . DB, DW, N, OR NS PACKAGE (TOP VIEW)



SN54LS245 . . . FK PACKAGE (TOP VIEW)



ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74LS245N	SN74LS245N
0°C to 70°C	SOIC - DW	Tube	SN74LS245DW	LS245
	3010 - DW	Tape and reel	SN74LS245DWR	L0243
	SOP – NS	Tape and reel	SN74LS245NSR	74LS245
	SSOP – DB	Tape and reel	SN74LS245DBR	LS245
	CDIP – J	Tube	SN54LS245J	SN54LS245J
–55°C to 125°C	CDII	Tube	SNJ54LS245J	SNJ54LS245J
	CFP – W	Tube	SNJ54LS245W	SNJ54LS245W
	LCCC – FK	Tube	SN54LS245FK	SN54LS245FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



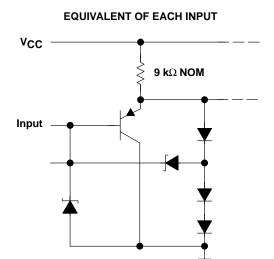
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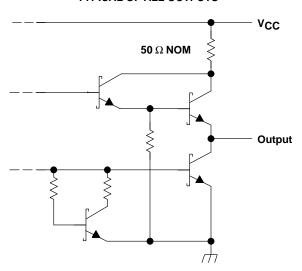
FUNCTION TABLE

INP	UTS	OPERATION			
OE	DIR	OPERATION			
L	L	B data to A bus			
L	Н	A data to B bus			
Н	Χ	Isolation			

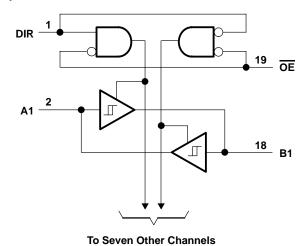
schematics of inputs and outputs



TYPICAL OF ALL OUTPUTS



logic diagram (positive logic)





SN54LS245, SN74LS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}		7 \
Input voltage, V _I (see Note 1)		7 \
Package thermal impedance, θ_{JA} (see Note 2):	DB package	70°C/V
	DW package	58°C/V
	N package	69°C/W
	NS package	60°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

recommended operating conditions

			N54LS24	5	SN74LS245			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
ІОН	High-level output current			-12			-15	mA
loL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SN54LS245, SN74LS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER			TEGT CONDITIONST		N54LS24	15	SN74LS245			
PARAME	IER	I ESI CONI	DITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
High-level input v	oltage			2			2			V
Low-level input vo	oltage					0.7			0.8	V
Input clamp voltag	ge	$V_{CC} = MIN,$	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
Hysteresis (V _{T+} -	- V _T _) A or B	$V_{CC} = MIN$		0.2	0.4		0.2	0.4		V
High lovel output	voltage	V _{CC} = MIN,	$I_{OH} = -3 \text{ mA}$	2.4	3.4		2.4	3.4		V
nigri-level output	voltage	$V_{IL} = V_{IL(max)}$	I _{OH} = MAX	2			2			V
Low lovel output	voltage	V _{CC} = MIN,	I _{OL} = 12 mA			0.4			0.4	V
Low-level output	voltage	$V_{IL} = V_{IL(max)}$ I_{OL}	I _{OL} = 24 mA						0.5	V
Off-state output current, high-level voltage applied		VCC = MAX, OE at 2 V	V _O = 2.7 V			20			20	μА
•	·	$\frac{V_{CC}}{OE} = MAX,$ OE at 2 V	V _O = 0.4 V			-200			-200	μА
Input current at	A or B	V MAY	V _I = 5.5 V			0.1			0.1	A
voltage	DIR or OE	ACC = MAY	V _I = 7 V			0.1			0.1	mA
I _{IH} High-level input current		$V_{CC} = MAX$,	V _{IH} = 2.7 V			20			20	μΑ
I _{IL} Low-level input current		$V_{CC} = MAX$,	V _{IL} = 0.4 V			-0.2			-0.2	mA
IOS Short-circuit output current§		V _{CC} = MAX	_	-40		-225	40		-225	mA
	Total, outputs high				48	70		48	70	
Supply current	upply current Total, outputs low	$V_{CC} = MAX$	Outputs open		62	90		62	90	mA
	Outputs at high Z				64	95		64	95	
	High-level input voltage Input clamp voltage Hysteresis (V _{T+} High-level output Coff-state output chigh-level voltage Input current at maximum input voltage High-level input complevel input current considerable. Low-level input complete complete input current considerable.	High-level output voltage Coff-state output current, high-level voltage applied Off-state output current, low-level voltage applied Input current at maximum input voltage High-level input current Low-level input current Short-circuit output current Supply current Total, outputs low	High-level input voltage Low-level input voltage Input clamp voltage Hysteresis (V _{T+} – V _{T-}) A or B VCC = MIN, VCC = MIN, VIH = 2 V, VIL = VIL(max) VCC = MIN, VIH = 2 V, VIL = VIL(max) Off-state output current, high-level voltage applied Off-state output current, low-level voltage applied Off-state output current, low-level voltage applied Input current at maximum input voltage High-level input current Low-level input current VCC = MAX, OE at 2 V VCC = MAX, V	High-level input voltage Low-level input voltage Input clamp voltage Hysteresis (V _{T+} - V _{T-}) A or B VCC = MIN, VIH = 2 V, VIH = VIH (max) Low-level output voltage Off-state output current, high-level voltage applied Off-state output current, low-level voltage applied Off-state output current, low-level voltage applied Input current at maximum input voltage DIR or OE High-level input current VCC = MIN, VIH = 2 V, VIH = 2 V	High-level input voltage Low-level input voltage Input clamp voltage Hysteresis (V _{T+} − V _{T-}) A or B VCC = MIN, I _I = −18 mA VCC = MIN, V _I = 2 V, V _I	PARAMETER TEST CONDITIONS† MIN TYP‡ High-level input voltage Cow-level input voltage VCC = MIN, I] = -18 mA Input clamp voltage VCC = MIN, VI] = -18 mA 0.2 0.4 Hysteresis (VT+ - VT_) A or B VCC = MIN, VI] = 2 V, VI] = VI] (max) IOH = -3 mA 2.4 3.4 High-level output voltage VCC = MIN, VI] = 2 V, VI] = VI] (max) IOL = 12 mA 2	High-level input voltage	PARAMETER TEST CONDITIONST MIN TYP\$ MAX MIN	High-level input voltage	High-level input voltage

[†] For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

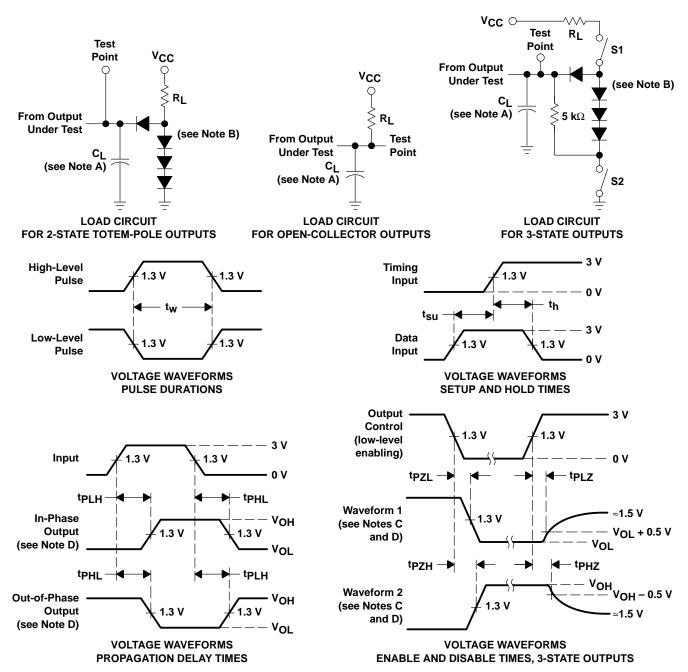
PARAMETER		TEST CO	MIN	TYP	MAX	UNIT	
tPLH	Propagation delay time, low- to high-level output	0 45 -5	D 007.0		8	12	
tPHL	Propagation delay time, high- to low-level output	$C_L = 45 \text{ pF},$	$R_L = 667 \Omega$		8	12	ns
tPZL	Output enable time to low level	C _I = 45 pF,	D: -667.0		27	40	no
tPZH	Output enable time to high level	OL = 45 pr,	$R_L = 667 \Omega$		25	40	ns
tPLZ	Output disable time from low level	$C_1 = 5 pF$,	R _I = 667 Ω		15	25	ns
tPHZ	Output disable time from high level	С _L = 5 рг,	K[= 007 \$2		15	28	115



 $[\]ddagger$ All typical values are at VCC = 5 V, TA = 25°C.

[§] Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

PARAMETER MEASUREMENT INFORMATION **SERIES 54LS/74LS DEVICES**



- NOTES: A. C_L includes probe and jig capacitance.
 - B. All diodes are 1N3064 or equivalent.
 - C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - D. S1 and S2 are closed for tpLH, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
 - E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
 - All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O \approx 50~\Omega$, $t_f \leq$ 1.5 ns, $t_f \leq$ 2.6 ns.
 - G. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
5962-8002101VRA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
5962-8002101VSA	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC
80021012A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
8002101SA	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC
JM38510/32803B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/32803BRA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
JM38510/32803BSA	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC
SN54LS245J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SN74LS245DBR	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS245DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74LS245DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74LS245J	OBSOLETE	CDIP	J	20		None	Call TI	Call TI
SN74LS245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS245N3	OBSOLETE	PDIP	N	20		None	Call TI	Call TI
SN74LS245NSR	ACTIVE	SO	NS	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54LS245FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54LS245J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SNJ54LS245W	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

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Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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28-Feb-2005

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